

ABSTRACT OF THE DISCLOSURE

A manufacturing apparatus of a semiconductor device includes a stage (12), a bonding head (14), a copying mechanism (22) mounted on the bonding head (14), and a controller (34) executing adjustment processing. In the adjustment processing, the controller (34) causes a facing surface (50) of the bonding head (14) to abut against a reference surface (110) of the stage (12) after setting the copying mechanism (22) to the locked state, then presses the facing surface (50) against the reference surface (110) after switching the copying mechanism (22) to a free state, and after that, switches the copying mechanism (22) to the locked state.

FIG. 7